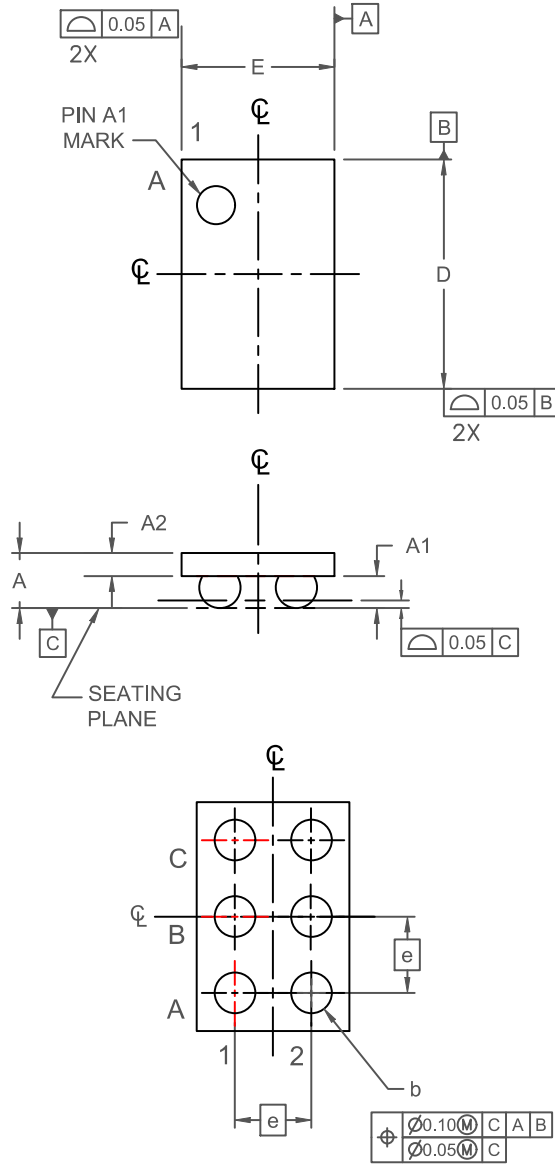


MECHANICAL CASE OUTLINE PACKAGE DIMENSIONS



WLCSP6 1.0x1.5x0.4
CASE 567PT
ISSUE A

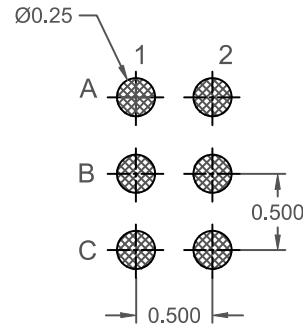
DATE 01 SEP 2021



NOTES: UNLESS OTHERWISE SPECIFIED

- A) DIMENSIONS ARE IN MILLIMETERS.
- B) DRAWING CONFORMS TO ASME Y14.5M-1994
- C) DATUM C APPLIES TO THE SPHERICAL OF THE SOLDER BALLS.

DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	---	---	0.40
A1	---	---	0.24
A2	0.13	0.15	0.16
b	0.24	0.26	0.29
D	0.95	1.00	1.05
E	1.45	1.50	1.55
e	0.50 BSC		



LAND PATTERN
RECOMMENDATION

*FOR ADDITIONAL INFORMATION ON OUR PB-FREE STRATEGY AND SOLDERING DETAILS, PLEASE DOWNLOAD THE ON SEMICONDUCTOR SOLDERING AND MOUNTING TECHNIQUES REFERENCE MANUAL, SOLDERRM/D.

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